

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Mizuki NAGAI et al. :
Serial No. Div. of 09/893,624 : **Attn: APPLICATION BRANCH**
Filed September 17, 2003 : Attorney Docket No. 2003_1338

**COPPER-PLATING LIQUID, PLATING
METHOD AND PLATING APPARATUS
(Rule 1.53(b) Divisional
of Serial No. 09/893,624 ,
Filed June 29, 2001)**

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the provisions of 37 CFR 1.56, 1.97 and 1.98, Applicants request consideration of ☒ the references listed on attached form PTO-1449 and/or ☐ the additional information identified below in paragraph 3. A legible copy of each reference listed on the form PTO-1449 and each U.S. patent application listed below is enclosed, except a copy is not provided for each reference previously cited by or submitted to the Patent Office in prior parent application Serial No. 09/893,624.

1a. ☒ This Information Disclosure Statement is submitted:

within three months of the filing date (or of entry into the National Stage) of the above-entitled application, **or**

before the mailing of a first Office Action on the merits or the mailing of a first Office Action after the filing of an RCE,

and thus no certification and/or fee is required.

1b. ☐ This Information Disclosure Statement is submitted

after the events of above paragraph 1a and prior to the mailing date of a final Office Action or a Notice of Allowance or an action which otherwise closes prosecution in the application, and thus:

(1) ☐ the certification of paragraph 2 below is provided, **or**

(2) ☐ the fee of \$180.00 specified in 37 CFR 1.17(p) is enclosed.

1c. ☐ This Information Disclosure Statement is submitted:

after the mailing date of a final Office Action or Notice of Allowance or action which otherwise closes prosecution in the application, and prior to payment of the issue fee, and thus:

the certification of paragraph 2 below is provided, and

the fee of \$180.00 specified in 37 CFR 1.17(p) is enclosed.

2. It is hereby certified

a. ☐ that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Statement, or


b. ☐ that no item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application and, to the knowledge of the person signing the certification after making reasonable inquiry, was known to any individual designated in §1.56(c) more than three months prior to the filing of the Statement.

3. ☒ Consideration of the following list of additional information (including any copending or abandoned U.S. application, prior uses and/or sales, etc.) is requested.

4. For each non-English language reference listed on the attached form PTO-1449, reference is made to:
- a. ☐ a full or partial English language translation submitted herewith,
 - b. ☐ a foreign patent office search report (in the English language) submitted herewith,
 - c. ☐ the concise explanation contained in the specification of the present application at page ,
 - d. ☐ the concise explanation set forth in the attached English language abstract,
 - e. ☐ the concise explanation set forth below or on a separate sheet attached to the reference:
5. ☐ A foreign patent office search report citing one or more of the references is enclosed.

Respectfully submitted,

Mizuki NAGAI et al.

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September 17, 2003

FORM PTO 1449 (modified)

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICELIST OF REFERENCES CITED BY APPLICANT(S)
(Use several sheets if necessary)

Date Submitted to PTO: September 17, 2003

ATTY DOCKET NO.
2003_1338SERIAL NO.
NEWAPPLICANT
Mizuki NAGAI et al.FILING DATE
September 17, 2003

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,695,810	12/1997	Dubin et al.			
	AB	6,110,011	8/2000	Somekh et al.			
	AC	6,197,181	3/2001	Chen			
	AD	2002-0004301	1/2002	Chen et al.			
	AE	6,267,853	7/2001	Dordi et al.			
	AF	6,413,436	7/2002	Aegerter et al.			
	AG	6,350,364	2/2002	Jang			
	AH	6,319,387	11/2001	Krishnamoorthy et al.			
	AI	6,251,235	6/2001	Talieh et al.			
		2002-0033340	3/2002	Cheung et al.			

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO	
	AJ	00/32835	6/2000	WIPO				
	AK							
	AL							
	AM							

OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)

	AO	Akihisa HONGO et al., "WAFER CLEANING APPARATUS", U.S. Patent Application Serial No. 09/572,432, filed May 17, 2000.						
	AP	Matsushita, Shinji, "Copper Electroplating Apparatus 'PARAGON' of Semitool, Loaded with Seed Layer Measuring Function, Seed Layer Strengthening/Repair Function", and, "Process Single Wafer Measuring Function", Semiconductor FPD World, vol. 19(10), pp. 122-124, Pressjournal (2000).						
	AQ							

EXAMINER

DATE CONSIDERED